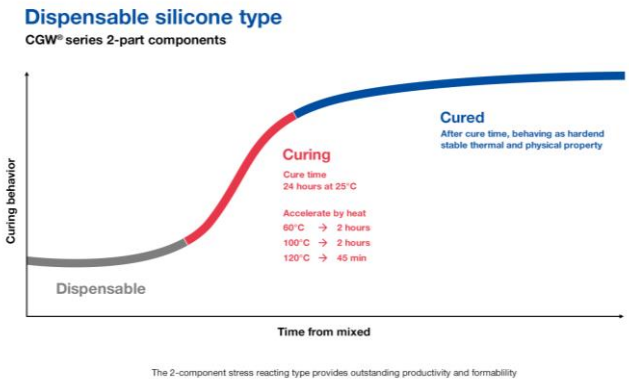
CGW® -3.6 (A/B)

Description

CGW® series are 2-part liquid silicone thermal conductive Gap Filler curable at room temperature. The curing time at room temperature is approximately 5 hours, and the grease softens during assembly, reducing stress on components such as PCBs, chips and cabinets. CGW® -3.6 offers the lowest molecular siloxane content level in the market.



The 2-component stress reacting type provides outstanding productivity and formability

Typical properties	
Mixing ratio	1:1
Color (A)	Light blue
Color (B)	White
Viscosity (A)*	260 Pa·s
Viscosity (B)*	230 Pa·s
Specific gravity (A)	2.85
Specific gravity (B)	2.85
Pot life at 25℃* (Up to twice of initial viscosity)	≧ 2hrs.
Cure time at 25℃	≦ 24hrs.
Thermal conductivity (ASTM D 5470)	3.6
Hardness (Type OO)	40
Flame rating (UL94) (≧0.15t)	V-0
Operating temperature	-40 ~ 150℃
Volume resistance	≧$1x10^{10}$Ω
Breakdown voltage	≧10kV/mm

*Viscosity measured by Brookfield DV-E, SC-14, 10rpm

Features

- Thermal conductivity: 3.6 W/m·K
- Two-part, liquid gap filling, dispensable material
- Room temperature curable
- Accelerate curing time by heating
- High thixotropic, holding three-dimensional shape
- Low stress, easy squeezing
- Specific gravity: 2.85

Packaging

- Dual cartridge (25cc x2, 100cc x2, 200cc x2)
- 330cc cartridge kit
- 600cc cartridge kit
- 25kg pail kit

*Only same lot number of A and B may be processed together

Application

- Electronic devices
- EV / PHEV / HV battery assembly
- Inverter / converter
- Optics (camera, LED modules)
- Medical electronics

Storage

Store in dry and cool place (1~30℃) without direct sunlight. Keep away from heat, flame and vibrating machine. If stored in long time, product can not use due to filler sedimentation. Best to use up shortly after purchasing.

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